

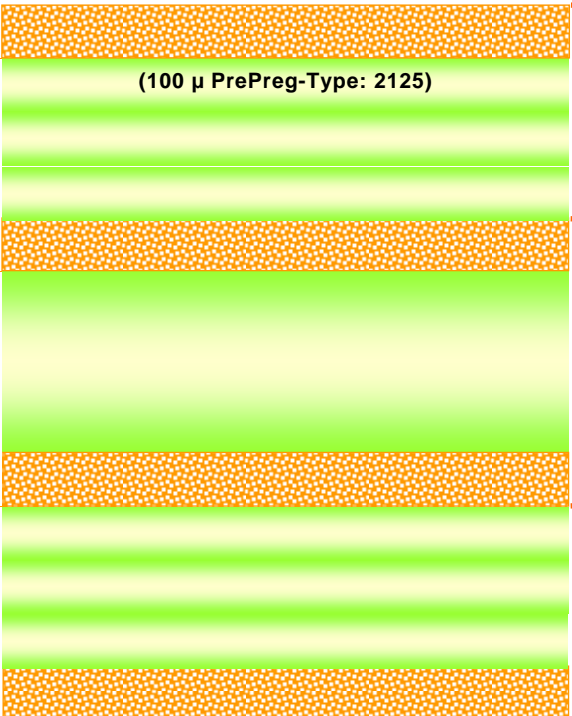
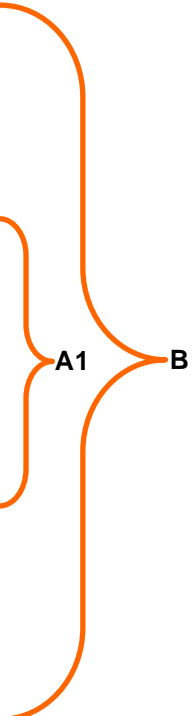
Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
---	---	---	---	---	---	-----------

04 236 FR4 125 L130.105 P10

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_236_FR4_125_L130.105_p10

Layers	in μ	Material	Build-Up	Assembly	
Layer-1	125 μ	Copper			
	100 μ	Prepreg			(100 μ PrePreg-Type: 2125)
	100 μ	Prepreg			
	100 μ	Prepreg			
Layer-2	105 μ	Copper			
	1300 μ	L-FR4			
Layer-3	105 μ	Copper			
	100 μ	Prepreg			
	100 μ	Prepreg			
	100 μ	Prepreg			
Layer-99	125 μ	Copper			

© Copyright by Printed Circuit Boards GmbH